

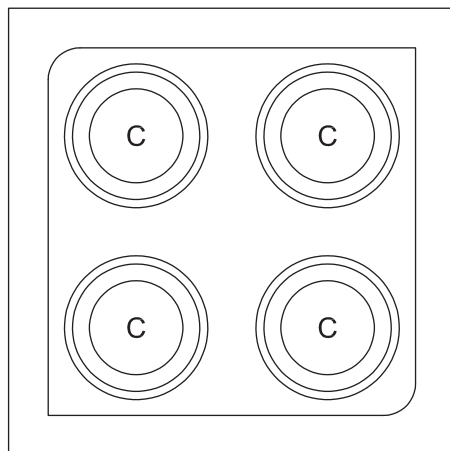
**PROCESS CPZ39R**  
**Transient Voltage Suppressor**  
**5 Volt Quad TVS Chip**



**PROCESS DETAILS**

Die Size	11 x 11 MILS
Die Thickness	3.94 MILS
Cathode Bonding Pad Areas (4)	3.54 MILS DIAMETER EACH
Top Side Metalization	Al - 30,000Å
Back Side Metalization	Au - 9,000Å

**GEOMETRY**



BACKSIDE ANODE R0

**GROSS DIE PER 5 INCH WAFER**

140,490

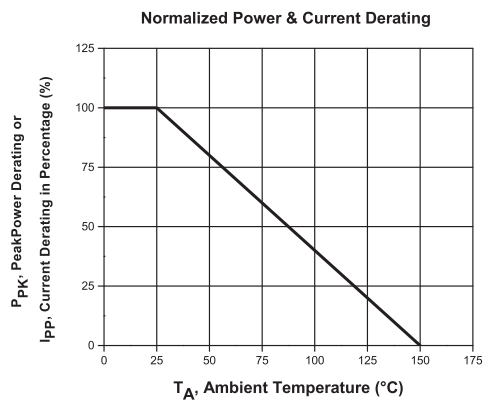
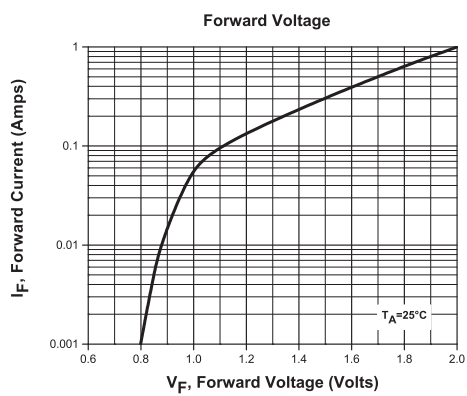
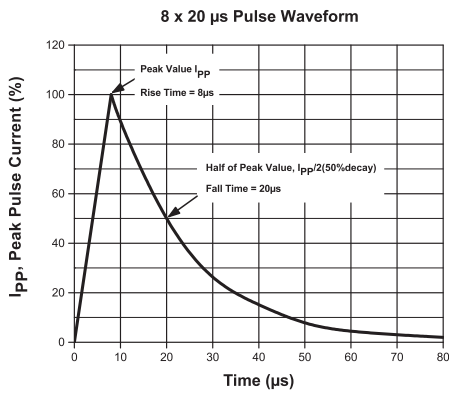
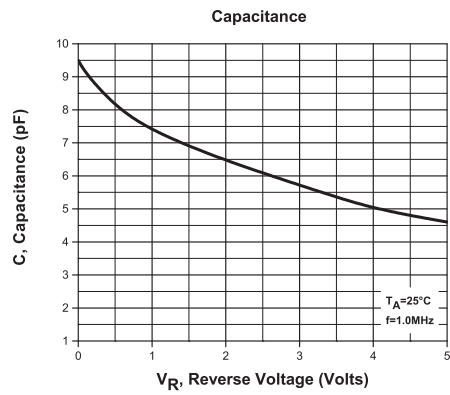
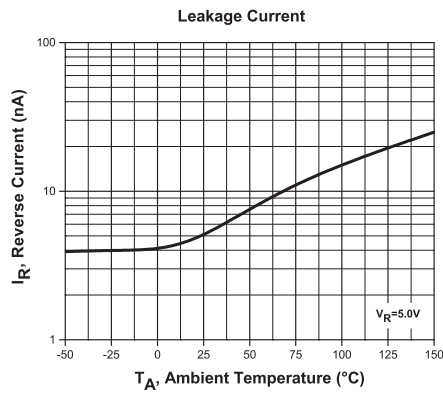
**PRINCIPAL DEVICE TYPE**

CMNTVS5V0

R0 (22-January 2013)

# PROCESS CPZ39R

## Typical Electrical Characteristics



R0 (22-January 2013)